

Supplementary information

Ultra-flexible temperature-insensitive strain sensor

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Table S1 Comparison of the performance of near-zero-TCR strain sensors that can apply strain to sensor materials through bending substrates. The minimum bending radii in some references were not illustrated or other methods were used to apply strain; therefore, the estimated values from the following formula are shown: $r = d_s/2\varepsilon$, where r is the minimum bending radius, d_s is the substrate thickness, and ε is the maximum applied strain. Remarkably, our sensor was thin and showed good flexibility in comparison. The TCR of $0.11\% \text{ K}^{-1}$ was sufficient to suppress the temperature effects, as demonstrated in this study.

Ref.	Sensor material	Process (Solution processes are underlined)	Substrate material	Substrate thickness	Maximum applied strain	TCR	Minimum bending radius
1	ITO, Pt	Sputtering	Zirconia	Unknown	0.0256%	$-0.0079\% \text{ K}^{-1}$	Unknown
2	Au, graphene	Transferring	Polyimide	30 μm	Unknown	Unclear	Unknown
3	ITO, Ag	Sputtering	Al_2O_3	380 μm	Unknown	$\sim 0.05\% \text{ K}^{-1}$ *	750 mm (Experiment)
4	Au	Evaporation	PET	100 μm	$< 0.75\%$	Unclear	> 6.7 mm (Estimation)
5	RuO_2 , glass powder	<u>Printing</u>	Al_2O_3	Unknown	Unknown	$\sim 0.01\% \text{ K}^{-1}$ *	Unknown
6	MWCNT, graphene	<u>Drop casting</u>	Polyimide	Unknown	$\sim 0.24\%$	$-0.0218 \Omega \text{ K}^{-1}$	Unknown
7	CNT, Ag NPs	<u>Screen printing</u>	PET	100 μm	Unknown	$\sim 0.03\% \text{ K}^{-1}$	Unknown
8	SWCNT, graphite	<u>Spray coating</u>	PET	250 μm	0.16%	Unclear	78 mm (Estimation)
9	Au NPs, ITO NPs	<u>Spin coating</u>	PDMS/PET	800/50 μm	1.8%	$-0.00007989\% \text{ K}^{-1}$	24 mm (Estimation)
10	Ag NPs	<u>Spin coating</u>	PET	250 μm	1%	$0.0019\% \text{ K}^{-1}$	13 mm (Estimation)
11	GNPs, Polysilazane	<u>Direct ink writing</u>	Paper	100 μm	0.5%	$0.002\% \text{ K}^{-1}$	10 mm (Estimation)
12	PEDOT:PSS	<u>Spin coating</u>	PET/PDMS	50/1000 μm	5%	$0.0093\% / \text{K}^{-1}$	1.25 mm ($\varepsilon=2\%$, Experiment) 0.5 mm ($\varepsilon=5\%$, Estimation)
This study	P3HT, BCF, Ag NPs	<u>Spin coating</u>	Polyimide	12.5 μm	6.1%	$0.11\% \text{ K}^{-1}$	0.14 mm (Experiment)

*Specific numbers are unclear

ITO: indium tin oxide, PET: polyethylene terephthalate, MWCNT: multi-walled carbon nanotube, CNT: carbon nanotube, NP: nanoparticle, SWCNT: single-walled carbon nanotube, PDMS: polydimethylsiloxane, GNPs: graphite nanoplatelets, PEDOT: poly(3,4-ethylenedioxythiophene), PSS: poly(styrenesulfonate), P3HT: poly(3-hexylthiophene-2,5-diyl), BCF: tris(pentafluorophenyl)borane

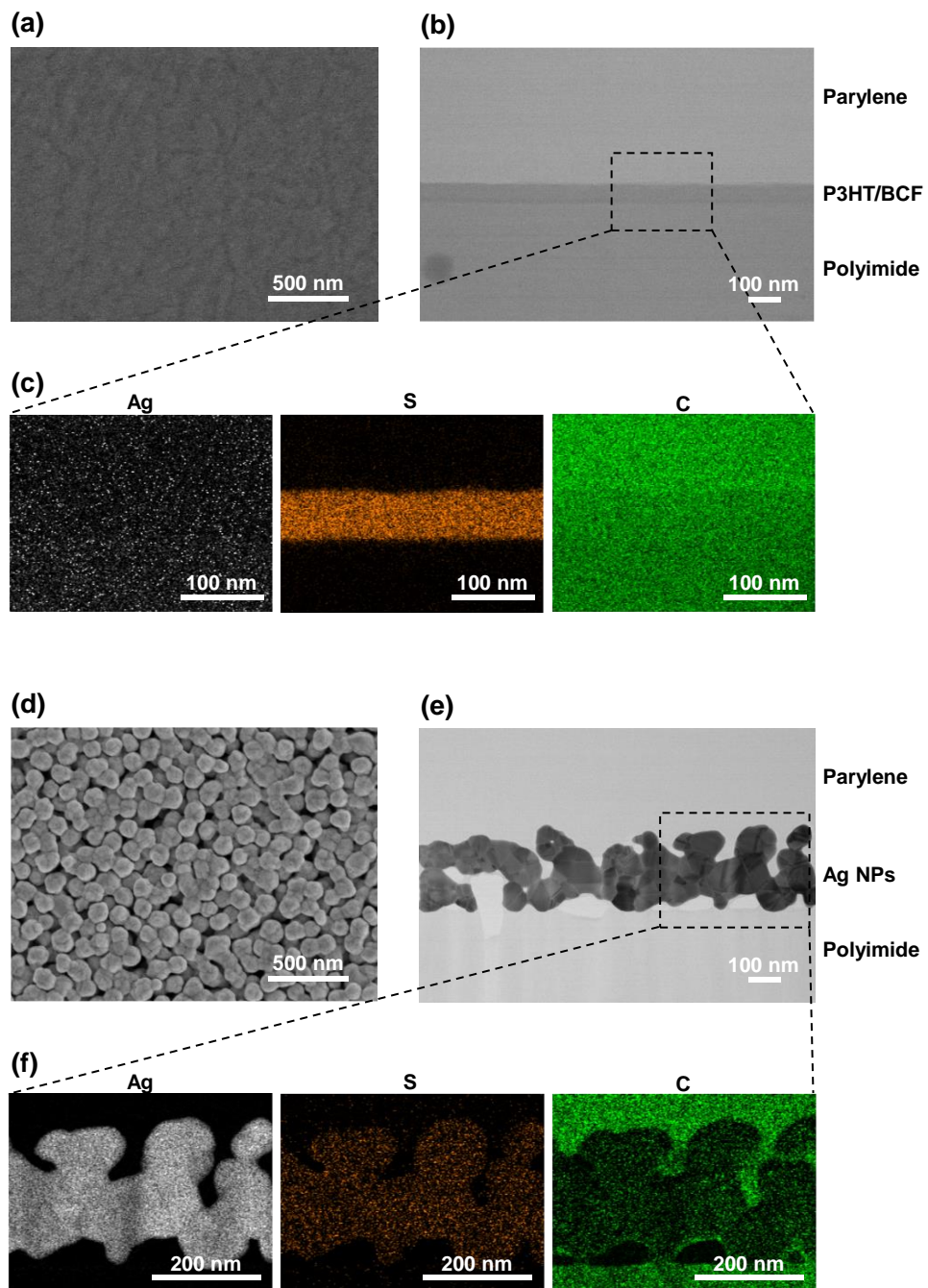


Fig. S1 Electron microscope images of nonhybrid films. (a–c) P3HT/BCF film without Ag NPs. (d–f) Ag NP film without P3HT and BCF. (a, d) SEM images of the films without parylene passivation observed from the surface. (b, e) Cross-sectional STEM images and (c, f) EDX elemental mapping images of the films. The elements are silver, sulfur, and carbon in order.

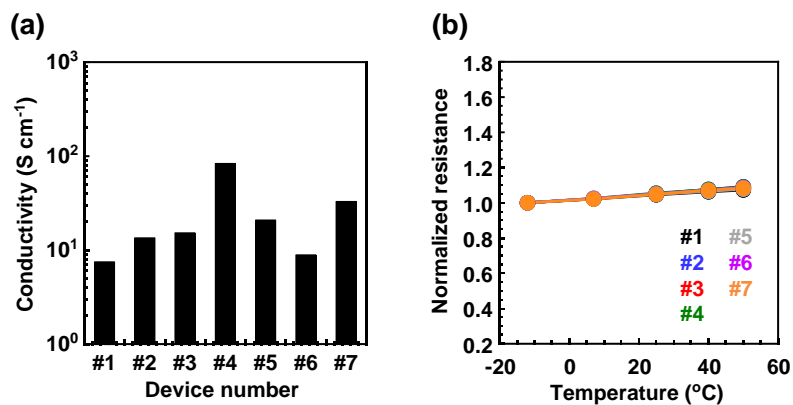


Fig. S2 Deviation of characteristics of seven near-zero-TCR strain sensors. (a) Conductivity of the sensors. (b) Resistance under different temperatures. The average value and standard deviation of TCR for the seven devices were 0.13% and 0.02% K⁻¹.

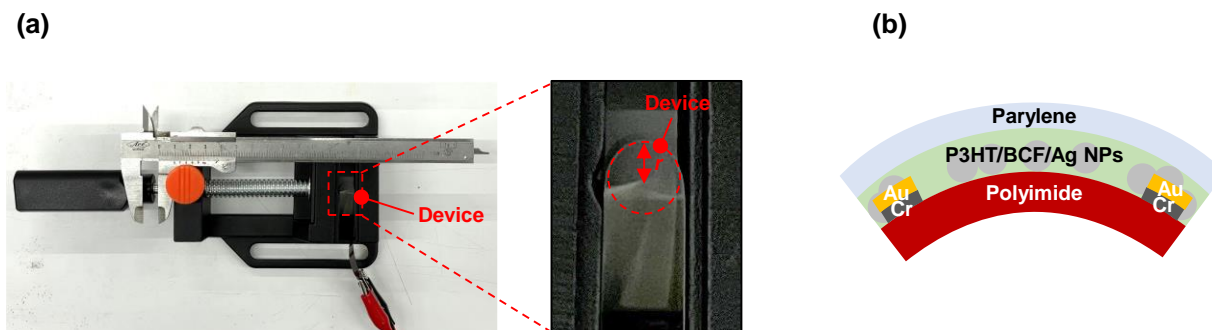


Fig. S3 Measurement method of strain sensors. (a) Photograph of the measurement system. (b) Schematic of the bent device that applies tensile strain to the sensor material.

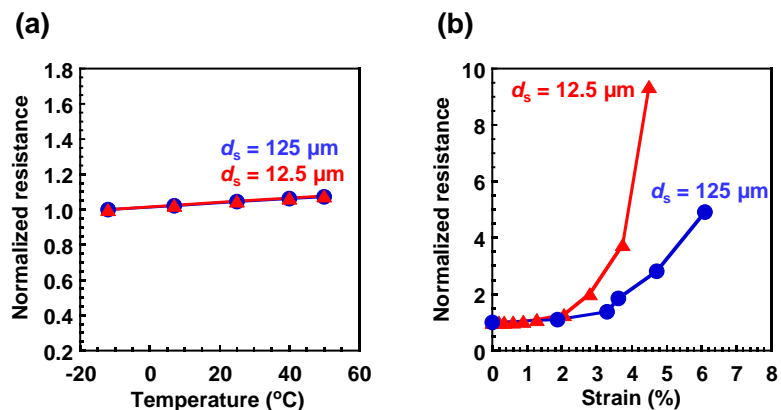


Fig. S4 Device characteristics of near-zero-TCR strain sensors for different substrate thickness. (a) Resistance under different temperatures. The TCR of the sensor with a substrate thickness of $12.5 \mu\text{m}$ was $+0.11\% \text{K}^{-1}$. (b) Strain sensitivity of the sensors.

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